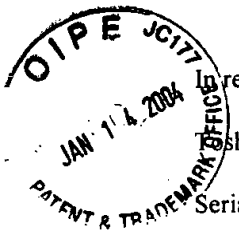


41
Docket No.: 50090-301

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re Application of

Shihiro YAMASHITA, et al.

Serial No.: 09/901,038

Filed: July 10, 2001

: Customer Number: 20277
:
: Confirmation Number: 6404
:
: Group Art Unit: 1763
:
: Examiner: M. Crowell
:

RECEIVED
JAN 16 2004
TC 1700

For: PLASMA PROCESSING SYSTEM IN WHICH WAFER IS RETAINED BY ELECTROSTATIC
CHUCK, PLASMA PROCESSING METHOD AND METHOD OF MANUFACTURING
SEMICONDUCTOR DEVICE

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is an Amendment in the above-identified application.

- ☒ No additional fee is required.
☐ Applicant is entitled to small entity status under 37 CFR 1.27
☐ Also attached:

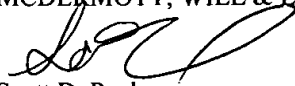
The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	18	20	0	\$18.00 =	\$0.00
Independent Claims	2	3	0	\$86.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
Total of Above Calculations					\$0.00

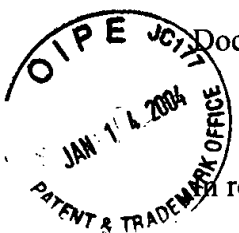
- ☐ Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.
- ☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

MCDERMOTT, WILL & EMERY


Scott D. Paul
Registration No. 42,984

600 13th Street, N.W.
Washington, DC 20005-3096
(202) 756-8000 SDP:kap
Facsimile: (202) 756-8087
Date: January 14, 2004



Docket No.: 50090-301

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re Application of

Toshihiro YAMASHITA, et al.

Application No.: 09/901,038

Filed: July 10, 2001

: Customer Number: 20277

: Confirmation Number: 6404

: Group Art Unit: 1763

: Examiner: M. Crowell

For: PLASMA PROCESSING SYSTEM IN WHICH WAFER IS RETAINED BY
ELECTROSTATIC CHUCK, PLASMA PROCESSING METHOD AND METHOD OF
MANUFACTURING SEMICONDUCTOR DEVICE

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AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following Amendment and Remarks are submitted in response to the non-final

Office Action dated October 17, 2003.